

APPROVAL SHEET

To :

Customer P/N :

UDE P/N : GSJ-ZZ-0003

Description : RJ45 1X4 Tab Up

T/H, Slim, Sink

5G Base-T

Contact Area : 50 μ " Min. Gold

LED : Without LED

Packing With Hard Tray



Spec No.
GSJ19001-00

Update Date
2019/6/19

Revision
A

Approved	Checked	Prepared



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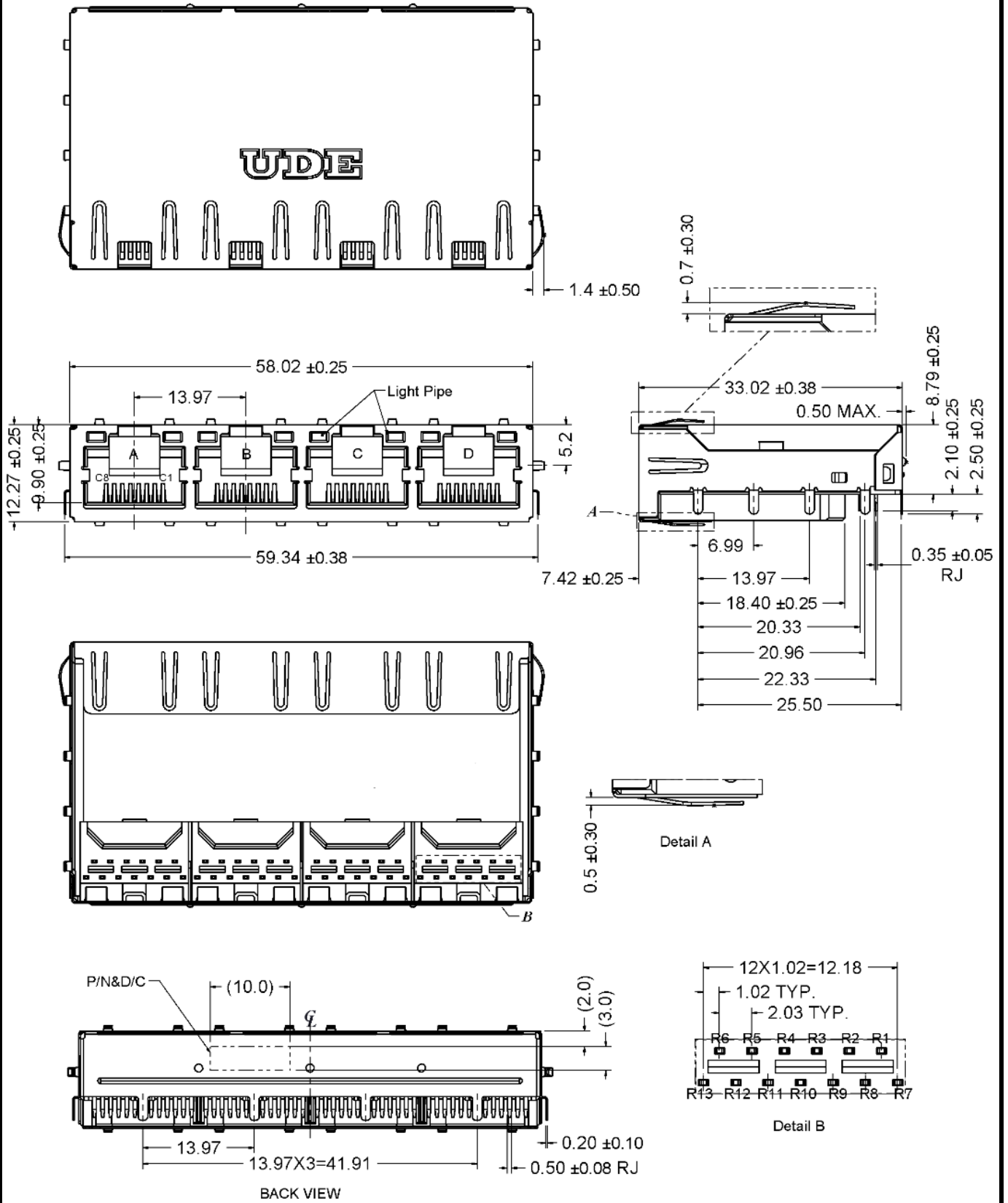
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<http://www.ude-corp.com/>

1. MECHANICAL DIMENSION

Product Dimension

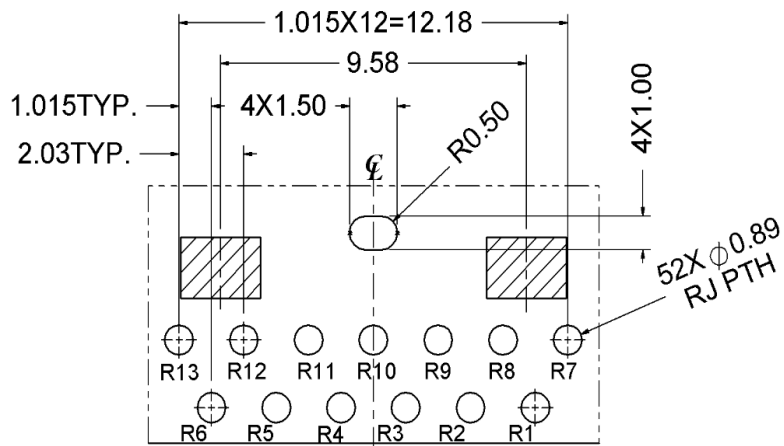
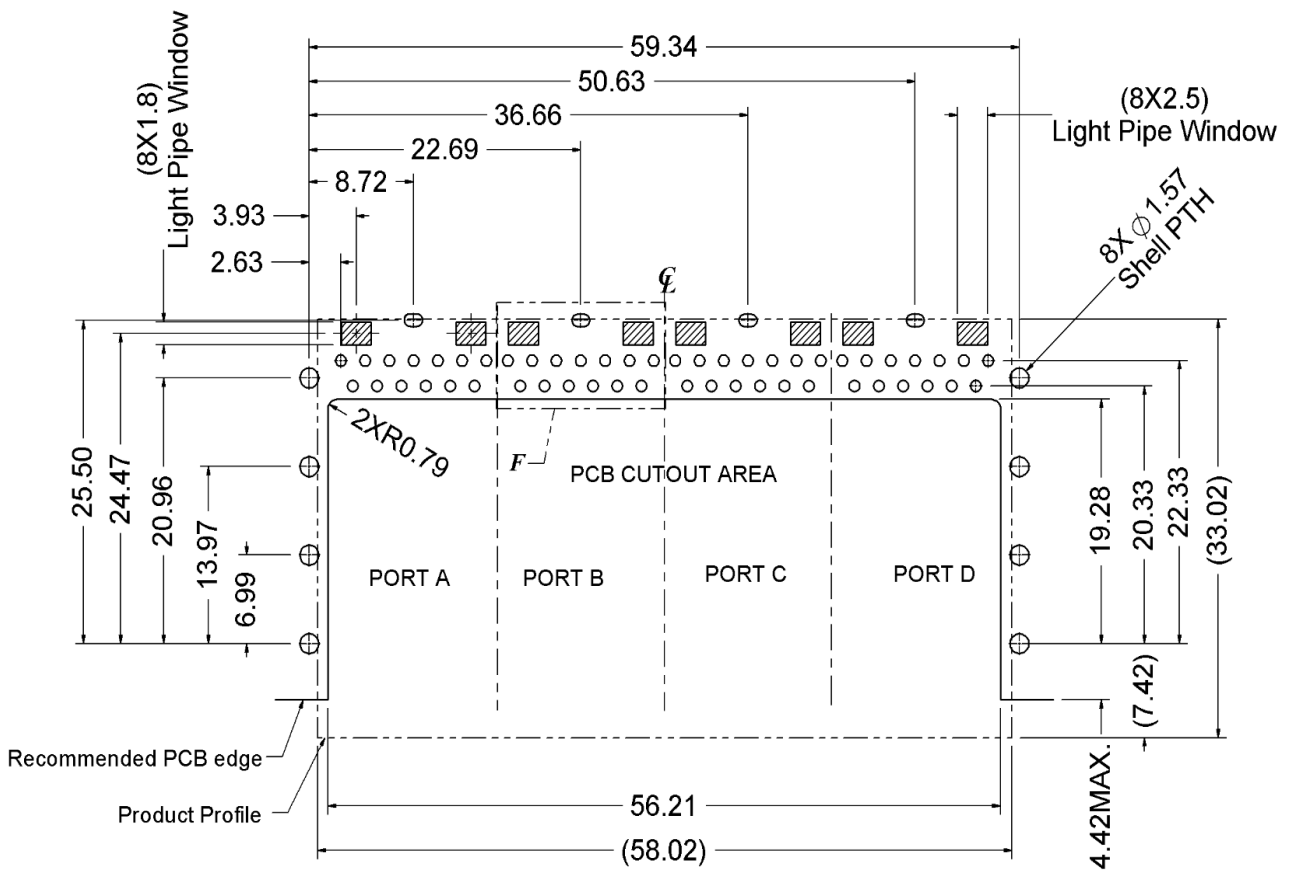
Unit:mm	General Tolerance :	X.X : ± 0.38
		X.XX : ± 0.20



Recommended PCB Layout. Component side of board

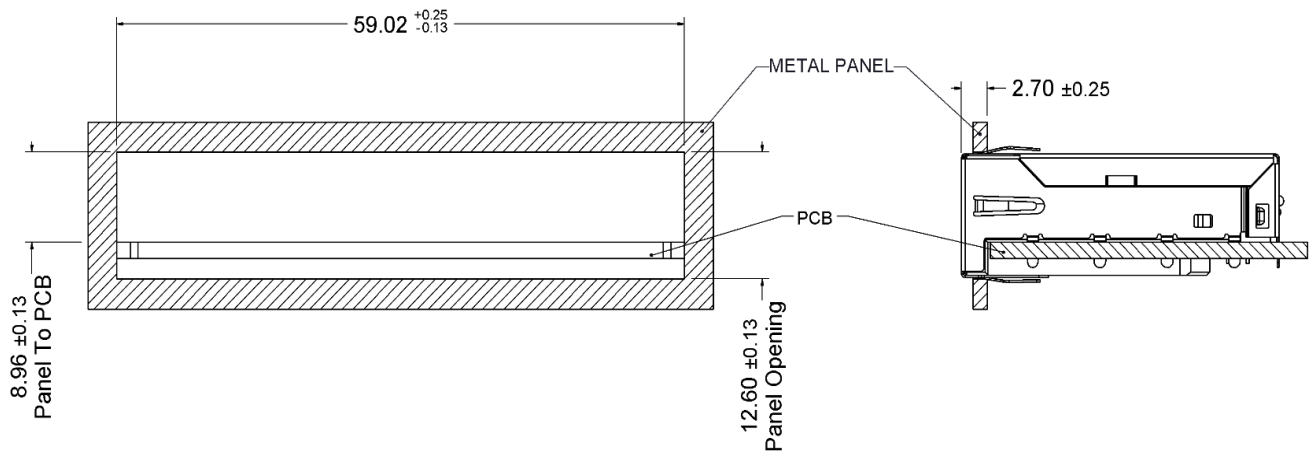
All dimension units are "mm".

All dimension tolerances are $\pm 0.05\text{mm}$ unless otherwise specified.



Detail F

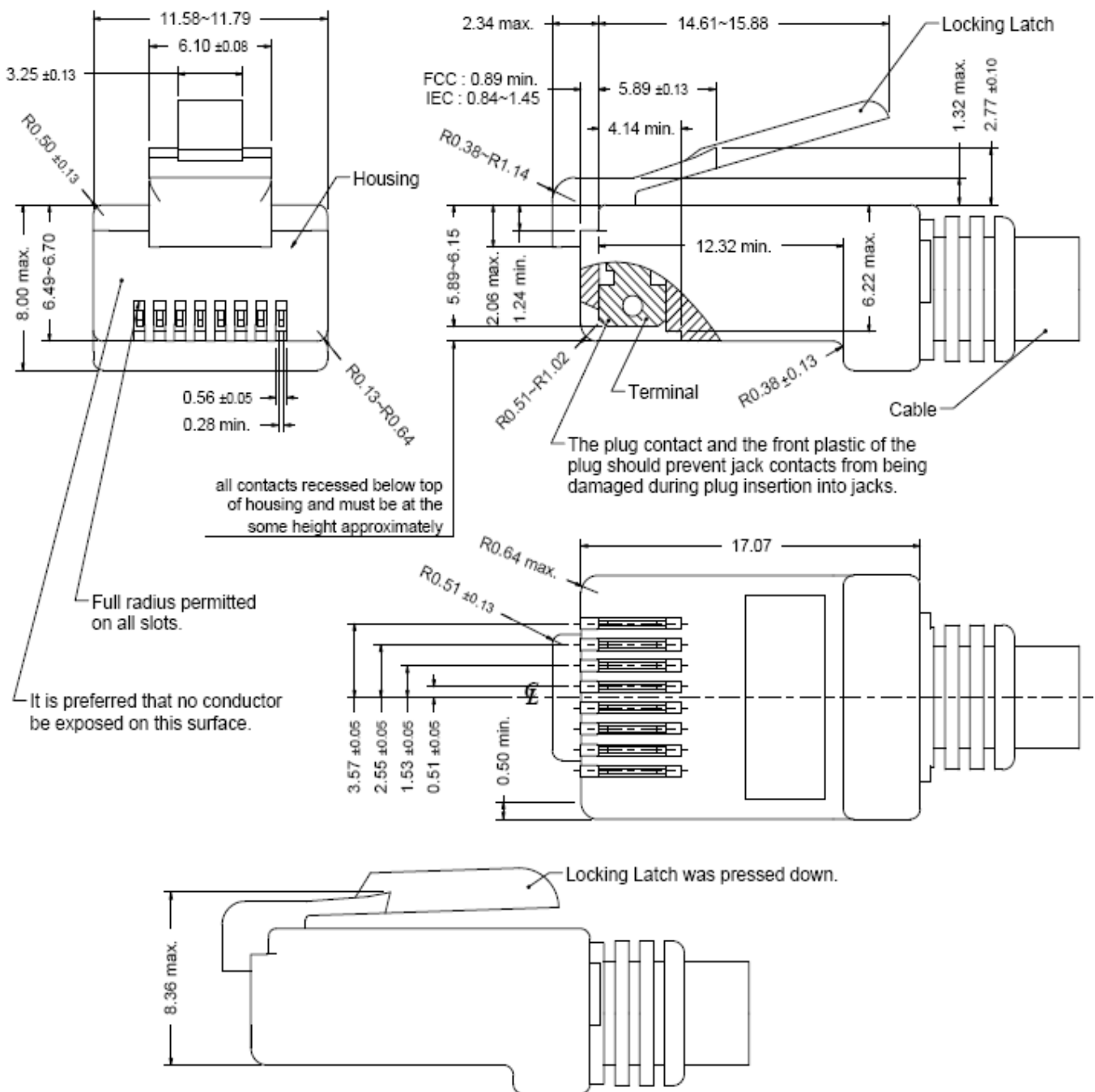
Recommended Panel cutout



◆ Packing Information

- 16 pcs finished goods per tray
- 8 trays(112 pcs finished goods) per inner box
- 4 Inner boxes(448 pcs finished goods) per master carton

2. Standard RJ45 Plug Specification



- All dimensions follow :
FCC subpart F, 68,500, Figure (C)(2)(i) & (C)(2)(ii) & (C)(3)(i)
IEC 60603-7
- All plugs must be meeting the requirements of plug Go & No-Go gauge.
Gauge follow : FCC subpart F, 68,500, Figure (C)(4)(i) & (C)(5)(i)
- There must be no damage to Housing and Locking Latch.
- There must be no nicks and cuts in cable.
- Durability : 750 cycles generally

3. REQUIREMENTS

Design and Construction

Product shall be of design, construction and physical dimensions specified on applicable.

Material

Terminal Parts (Underplating : 50 μ " min. Nickel overall)

RJ Terminal : Phosphor Bronze, Thickness=0.30mm

Finish : Contact Area : 50 μ " min. Gold

Input Terminal : Brass, Thickness=0.35mm

Finish : 100 μ " min. Bright Tin

Case Terminal : Brass, Thickness=0.30mm

Finish : 100 μ " min. Bright Tin

Link Terminal : Brass, Thickness=0.35mm

Finish : 100 μ " min. Bright Tin

Ground Terminal : Phosphor Bronze, Thickness=0.25mm

Finish : 100 μ " min. Bright Tin

Plastic Parts <UL94V-0>

Housing : LCP, Black

Case : PA9T, Black

Light Pipe : PC,Transparent

Shield Parts :

Shell : Phosphor Bronze, Thickness=0.20mm

Finish : 30 μ " min. Nickel overall

4. Operating and Storage Temperature

Operating Temperature : 0°C to +70°C

Storage Temperature : -40°C to +85°C

5. RJ45 specifications

Insulation Resistance : 500MΩ min.

Insertion force with the latch depressed : 20N max.

Removal force with the latch depressed : 20N max.

Locking Force of Plug Latch : 50N min. @ 60+/-5 sec.

Durability : 2500 cycles

6. Performance and Test Description

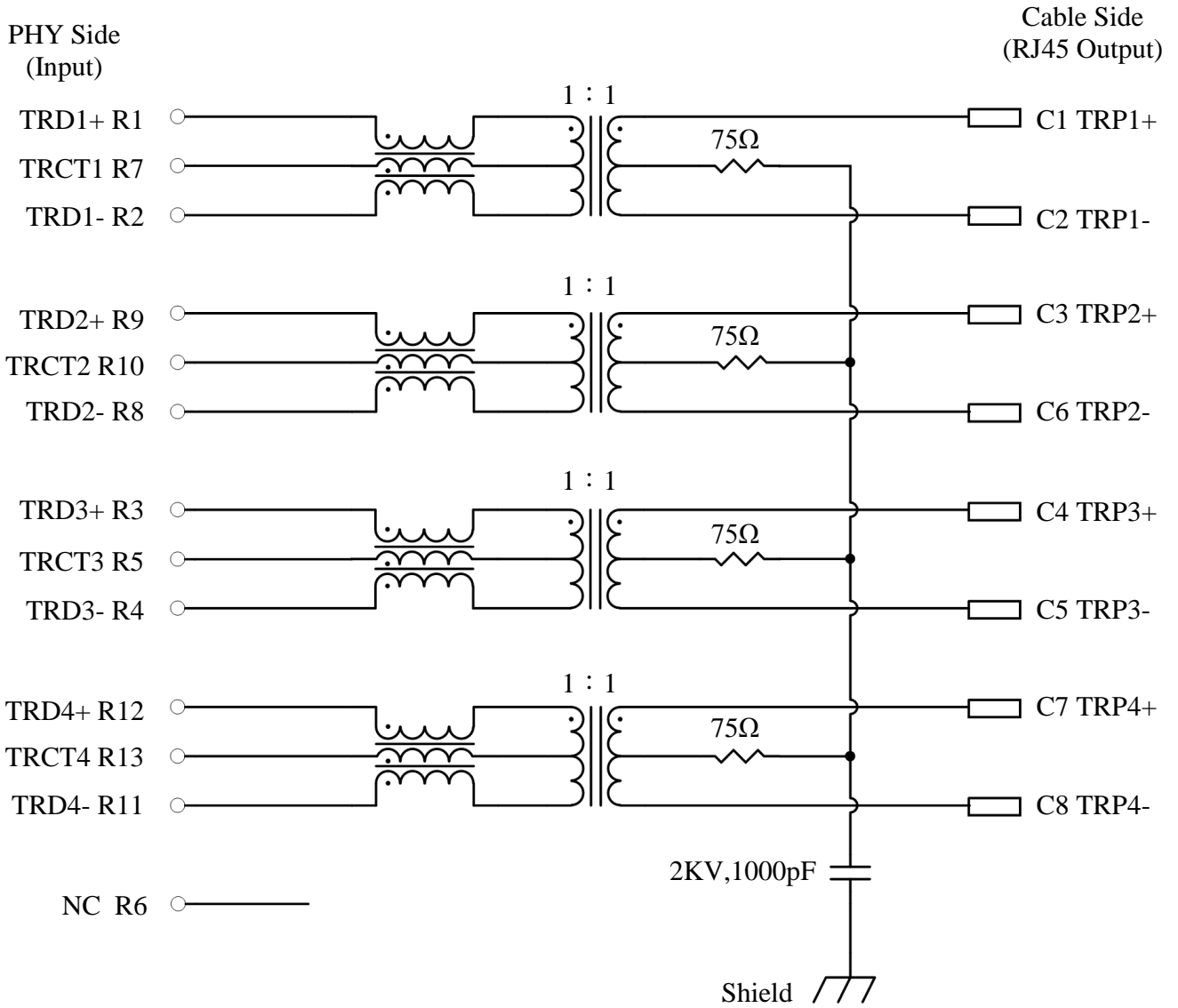
Product is designed to meet electrical, mechanical and environmental performance requirements specified in below table.

All tests are performed at ambient environmental conditions per MIL-STD-1344A and EIA-364 unless otherwise specified.

7. Packaging and Packing

All parts shall be packaged and packed to protect against physical damage, corrosion and deterioration during shipment and storage.

8. ELECTRICAL CHARACTERISTICS @25°C



Transmitter filter & Receiver filter

Type : Balance low pass 100Ω impedance

Insertion loss :	1~50MHz	-0.5dB Max.
	50~125MHz	-1.0dB Max.
	125~200MHz	-2.0dB Max.
	200~250MHz	-2.5dB Max.

Return loss :	1~50MHz	-20dB Min.	load 100Ω
	50~250MHz	-20+15*log(Freq MHz/40MHz) dB Min load 100Ω	

Reflected CM to Diff Conversion(REF)

1MHz	-30dB Min.
50MHz	-30dB Min.
100MHz	-27dB Min.
200MHz	-24dB Min.
250MHz	-23dB Min.

CM to DM Conversion(REF)

1~50MHz	-35dB Min.
125MHz	-30dB Min.
200MHz	-27dB Min.
250MHz	-23dB Min.

Reflected Diff to CM Conversion (REF)

1~10MHz	-48dB Min.
10~250MHz	-48+19*log(Freq MHz/10MHz) dB Min

CM to CM Attenuation (REF)

1~200MHz	-25dB Min.
200~250MHz	-20dB Min.

Cross Talk (REF)

1~125MHz	-30dB Min.
125~250MHz	-25dB Min.

Inductance @ 25°C, 100KHz, 100mV, 8mA DC BIAS

Input(TRD1+,TRD1-); (TRD2+,TRD2-); (TRD3+,TRD3-); (TRD4+,TRD4-):160uH Min.

HiPot Test

PHY Side(input) To Cable Side(output) : 1500Vac 60s or 2250Vdc 60s

9. WAVE SOLDERING TEMPERATURE PROFILE

Note :

The measuring point for the specified temperature shall be on the soldered part of the lead.

